# Handbook of Advanced Nondestructive Evaluation

Nathan Ida • Norbert Meyendorf Editors

# Handbook of Advanced Nondestructive Evaluation

With 949 Figures and 43 Tables



*Editors* Nathan Ida Department of Electrical and Computer Engineering The University of Akron Akron, OH, USA

Norbert Meyendorf Center for Nondestructive Evaluation Iowa State University Center for Nondestructive Evaluation Ames, IA, USA

ISBN 978-3-319-26552-0 ISBN 978-3-319-26553-7 (eBook) ISBN 978-3-319-30122-8 (print and electronic bundle) https://doi.org/10.1007/978-3-319-26553-7

#### © Springer Nature Switzerland AG 2019

This work is subject to copyright. All rights are reserved by the Publisher, whether the whole or part of the material is concerned, specifically the rights of translation, reprinting, reuse of illustrations, recitation, broadcasting, reproduction on microfilms or in any other physical way, and transmission or information storage and retrieval, electronic adaptation, computer software, or by similar or dissimilar methodology now known or hereafter developed.

The use of general descriptive names, registered names, trademarks, service marks, etc. in this publication does not imply, even in the absence of a specific statement, that such names are exempt from the relevant protective laws and regulations and therefore free for general use.

The publisher, the authors, and the editors are safe to assume that the advice and information in this book are believed to be true and accurate at the date of publication. Neither the publisher nor the authors or the editors give a warranty, express or implied, with respect to the material contained herein or for any errors or omissions that may have been made. The publisher remains neutral with regard to jurisdictional claims in published maps and institutional affiliations.

This Springer imprint is published by the registered company Springer Nature Switzerland AG. The registered company address is: Gewerbestrasse 11, 6330 Cham, Switzerland

## Preface

The Internet of Things (IoT) and the next generation of industrial production (Industry 4.0) encompass the complete networking of all industrial areas. New production techniques as, for example, 3D printing will allow efficient on-time production of low numbers of unique parts. A significant aspect is quality and maintainability of these (sometimes) unique structures and components. Nondestructive evaluation or testing (NDE or NDT) must, necessarily, follow these trends by not only adapting NDE techniques to new technologies but also introducing the capability of cyber systems into the inspection and maintenance processes and anticipating future needs. These new challenges and capabilities will also boost the application of unconventional and new NDE principles to industrial applications.

Industry 4.0 and the ability to tailor individual components to the customer's needs will significantly impact the way we provide nondestructive inspection and evaluation. NDE must be integrated into the production process by networking with processes and production steps during manufacturing. This will result in a paradigm shift in industrial quality management and NDE. Classical concepts based on comparison of multiple similar components and statistical analysis will not be applicable under these conditions, raising the impact of the human factor. Availability of specialists capable of making the right decisions based on NDE results, knowledge about the material and the components, loading conditions, and NDE modeling of NDE experiments will be essential for the future.

This new generation of NDE specialists need to have a broad overview of conventional and new, advanced NDE techniques. A considerable amount of overview literature for common NDE techniques that are usually based on standards is available worldwide. Several organizations offer NDE training classes and certification for inspectors for the standard techniques. Other new methods that may, at present, be in experimental, laboratory stages but have the potential for application for future inspection tasks can only be found in specific scientific journals and, sometimes, may not even be considered as NDE candidates. However, to solve future NDE tasks, the specialist should have a clear understanding of what is possible without going into too many details.

The present book intends to bridge this gap between conventional common sense NDE methods of the present and the past and advanced techniques that provide and guide new opportunities for inspections for the next generation of NDE. As is often the case, many methods described here have evolved from prior experience and from pressing needs in industrial inspection. The reader will find that the offerings in the present handbook is a healthy mixture of methods that are in limited use, those that are at various stages of development and some that are envisioned for the future.

This handbook is structured on the lines of accepted NDE principles but focuses on advanced methods of measurement or data analysis. It is not the intent of the book to introduce the basics of NDE principles. The exceptional contributions that make up this handbook were made by specialists worldwide working on advanced NDE techniques. The editors are grateful that so many excellent contributions have been submitted and are happy to present this unique overview of advanced NDE techniques. The task of keeping up to date, of course, can never be completed and any attempt at doing so can only be a snapshot of present activities. In this spirit, the online version of the handbook will be updated and enlarged in the future to keep the contents up to date.

We sincerely thank all those involved in the writing, editing, and production of this work.

June 2019

Nathan Ida Norbert Mayendorf

# Contents

#### Volume 1

Part	I Acoustic Techniques	1
1	Physical Basis for Ultrasonic Acoustics	3
2	Ultrasonic Wavefield Imaging Jennifer E. Michaels	43
3	Acoustic Microscopy Frank Schubert, Martin Barth, Raffael Hipp, and Bernd Köhler	75
4	Acoustic Emission	115
5	Guided Wave Testing	141
6	Laser-Induced Surface Acoustic Waves for Material Testing Dieter Schneider	171
7	The Acousto-elastic Effect and Its Use in NDE	235
8	Nonlinear Acoustics Younho Cho and Weibin Li	251
9	<b>Local Acoustic Resonance Spectroscopy</b>	271
10	Nonlinear Resonant Acoustic SpectroscopyBart Van Damme and Koen Van Den Abeele	295

Part	t II Optical Techniques	325
11	Surface Brillouin Scattering Arthur G. Every and J. Darrell Comins	327
12	Interferometric Methods in NDE	361
13	Shearography Lianxiang Yang and Junrui Li	383
14	White Light Interferometry	421
15	<b>Optical Coherence Tomography for NDE</b> Jonas Golde, Lars Kirsten, Christian Schnabel, Julia Walther, and Edmund Koch	469
16	Ellipsometry Jian Chen and Qiwen Zhan	513
17	Raman ScatteringRudolph M. Erasmus and J. Darrell Comins	541
18	<b>Optical Fiber Methods in Nondestructive Evaluation</b>	595
	5 6	
Part	t III Electromagnetic Techniques	643
Part 19	Eddy Current Testing         Zhenmao Chen, Cherdpong Jomdecha, and Shejuan Xie	<b>643</b> 645
Part 19 20	Eddy Current Testing         Zhenmao Chen, Cherdpong Jomdecha, and Shejuan Xie         High-Frequency Eddy Current Techniques         Susanne Hillmann, Martin H. Schulze, and Henning Heuer	<b>643</b> 645 729
Part 19 20 21	Eddy Current Testing         Zhenmao Chen, Cherdpong Jomdecha, and Shejuan Xie         High-Frequency Eddy Current Techniques         Susanne Hillmann, Martin H. Schulze, and Henning Heuer         Eddy Current Tomography         Antonello Tamburrino and Guglielmo Rubinacci	<b>643</b> 645 729 757
Part 19 20 21 22	Eddy Current Testing         Zhenmao Chen, Cherdpong Jomdecha, and Shejuan Xie         High-Frequency Eddy Current Techniques         Susanne Hillmann, Martin H. Schulze, and Henning Heuer         Eddy Current Tomography         Antonello Tamburrino and Guglielmo Rubinacci         Motion-Induced Eddy Current Testing         Hartmut Brauer and Marek Ziolkowski	<ul> <li>643</li> <li>645</li> <li>729</li> <li>757</li> <li>781</li> </ul>
Part 19 20 21 22 23	Eddy Current Testing	<ul> <li>643</li> <li>645</li> <li>729</li> <li>757</li> <li>781</li> <li>827</li> </ul>
Part 19 20 21 22 23 24	Eddy Current Testing         Zhenmao Chen, Cherdpong Jomdecha, and Shejuan Xie         High-Frequency Eddy Current Techniques         Susanne Hillmann, Martin H. Schulze, and Henning Heuer         Eddy Current Tomography         Antonello Tamburrino and Guglielmo Rubinacci         Motion-Induced Eddy Current Testing         Hartmut Brauer and Marek Ziolkowski         Low Field Methods (GMR, Hall Probes, etc.)         Vivek T. Rathod, Portia Banerjee, and Yiming Deng         Micromagnetic Materials Characterization         Klaus Szielasko and Ralf Tschuncky	<ul> <li>643</li> <li>645</li> <li>729</li> <li>757</li> <li>781</li> <li>827</li> <li>881</li> </ul>

#### Contents

#### Volume 2

Par Tec	t IV Electromagnetic Microwave and Millimeter-Wave hniques	927
26	Microwave and Millimeter Wave Nondestructive Testing and         Evaluation	929
27	Terahertz Techniques in NDE	967
28	Ground Penetrating Radar	987
Par	t V X-Ray Techniques	1025
29	Processing of X-Ray Images	1027
30	<b>X-Ray Phase Contrast Methods</b>	1053
31	X-Ray Tomography Johann Kastner and Christoph Heinzl	1095
32	<b>3D X-Ray Tomography: Basics and Latest Developments</b> Theobald O. J. Fuchs and Randolf Hanke	1167
33	Grazing Incidence X-Ray Reflectivity and Scattering Brian K. Tanner	1181
Par	t VI Particle Methods	1215
34	<b>Neutron Radiography and Tomography</b> Wolfgang Treimer	1217
35	<b>Positron Annihilation</b> Luca Chiari and Masanori Fujinami	1301
Par	t VII Thermal Techniques	1347
36	Physical Basics of Thermal Techniques of Nondestructive         Evaluation         Vladimir P. Vavilov	1349
37	Passive Thermography, Thermal ImagingHelmut Budzier and Gerald Gerlach	1371

38	Active Thermography	1401
39	Thermal Wave Techniques Gunnar Suchaneck, Agnes Eydam, and Gerald Gerlach	1419
40	Sonothermic Techniques in Nondestructive Evaluation	1479
41	Induction Thermography of Surface Defects	1497
Par	t VIII Special Techniques for Signal and Data Analysis	1523
42		
	Signal Processing for NDE Masoud Vejdannik, Ali Sadr, Victor Hugo C. de Albuquerque, and João Manuel R. S. Tavares	1525
43	Signal Processing for NDEMasoud Vejdannik, Ali Sadr, Victor Hugo C. de Albuquerque, andJoão Manuel R. S. TavaresDigital Image Correlation Techniques for NDE and SHMChristopher Niezrecki, Javad Baqersad, and Alessandro Sabato	1525 1545
43 44	Signal Processing for NDE         Masoud Vejdannik, Ali Sadr, Victor Hugo C. de Albuquerque, and         João Manuel R. S. Tavares         Digital Image Correlation Techniques for NDE and SHM         Christopher Niezrecki, Javad Baqersad, and Alessandro Sabato         Structural Health Monitoring         Bianca Weihnacht, Uwe Lieske, Tobias Gaul, and Kilian Tschöke	1525 1545 1591

### **About the Editors**



Nathan Ida is currently distinguished professor of Electrical and Computer Engineering at The University of Akron in Akron. Ohio, where he has been since 1985. His current research interests are in the areas of electromagnetic nondestructive testing and evaluation of materials at low and microwave frequencies with particular emphasis on theoretical issues, on all aspects of modeling and simulation and on related issues stemming from research in NDE. Starting with modeling of eddy current and remote field phenomena, and continuing with high frequency methods for microwave NDE, his work now encompasses the broad aspects of computational electromagnetics where he has contributed to both the understanding of the interaction of electromagnetic fields with materials and the development of new methods and tools for numerical modeling and simulation for, and beyond, NDE. Other areas of current interinclude electromagnetic wave propagation, est theoretical issues in computation, as well as in communications and sensing, especially in low power remote control and wireless sensing. Much of this work has found its way into practice through industrial relations and consulting across industries as diverse as power generation, polymers, steel, medical, and software, spanning the globe. Dr. Ida has published extensively on electromagnetic field computation, parallel and vector algorithms and computation, nondestructive testing of materials, surface impedance boundary conditions, sensing, and others, in over 400 publications. He has written nine books: two on computation of electromagnetic fields (one in its second edition), one on modeling for nondestructive testing, one on nondestructive testing with microwaves, a textbook on engineering

electromagnetics (now in its fourth edition), a textbook on sensing and actuation (now in its second edition), a book on the use of surface impedance boundary conditions, and others, including on ground penetrating radar and industrial sensing based on microwaves. Dr. Ida is a life fellow of the Institute of Electric and Electronics Engineers (IEEE), a fellow of the American Society of Nondestructive Testing (ASNT), a fellow of the Applied Computational Electromagnetics Society (ACES), and a fellow of the Institute of Electronics and Technology (IET). Dr. Ida teaches electromagnetics, antenna theory, electromagnetic compatibility, sensing, and actuation, as well as computational methods and algorithms.

Dr. Ida received his B.Sc. in 1977 and M.S.E.E. in 1979 from the Ben-Gurion University in Israel, and his Ph.D. from Colorado State University in 1983.



**Norbert Meyendorf** retired in fall 2018 as deputy director of the Center for Nondestructive Evaluation and professor in the Aerospace Engineering department at the Iowa State University in Ames, Iowa. Before joining ISU in 2016 he had several appointment and ranks. The most recent are:

Branch Director at the Fraunhofer Institute for Nondestructive Testing IZFP and later IKTS, director of the International University of Dayton/Fraunhofer Research Center at the School of Engineering at the University of Dayton, organizing collaborative projects between Fraunhofer and University of Dayton, and Program Director of the Master program "Nondestructive Testing, M. Sc. (NDT)" at the Dresden International University (DIU) between 2011 and 2015.

Norbert Meyendorf continues to be active as adjunct professor for micro- and nano-NDE at the University of Dresden and adjunct professor at the Department for Chemical and Materials Engineering, University of Dayton.

He is the author or coauthor of more than 300 peerreviewed journal articles, contributions to edited proceedings, technical reports, and numerous oral presentations on conferences, meetings, workshops, etc. He is editor in chief of the *Journal of Nondestructive Evaluation* and edited several books and conference proceedings. His areas of expertise include solid state physics and physical analytics, welding metallurgy, materials testing, nondestructive evaluation (NDE), and structural heath monitoring (SHM), for instance.

Since 2001, he has been chairman or co-chairman of several conferences within the SPIE International Symposium on Nondestructive Evaluation for Health Monitoring and Diagnostics and later the Symposium for Smart Structures and NDE. In 2005, 2006, 2012, and 2013, he was chair or co-chair of the whole SPIE Symposium. In 2018 he became fellow of SPIE.

Norbert Meyendorf was founder and chair of two expert committees of the German Society for Non-Destructive Testing (DGZfP), the Expert Committees for "Structural Health Monitoring" and "Materials Diagnostics." Between 2016 and 2018, he reorganized and directed the ASNT Section Iowa.

# Contributors

Koen Van Den Abeele Physics, Kulak Kortrijk Campus, Kortrijk, Belgium

**Dimitrios G. Aggelis** Department of Mechanics of Materials and Constructions (MeMC), Vrije Universiteit Brussel (VUB), Brussels, Belgium

**Portia Banerjee** SGT Inc., NASA Ames Research Center, Mountain View, CA, USA

Javad Baqersad Department of Mechanical Engineering, Kettering University, Flint, MI, USA

Martin Barth Ultrasonic Sensors and Methods, Fraunhofer IKTS, Dresden, Germany

Michael Mathias Becker Fraunhofer Institute for Nondestructive Testing IZFP, Saarbrücken, Germany

Hartmut Brauer Technische Universitaet Ilmenau, Ilmenau, Germany

**Helmut Budzier** Institute of Solid State Electronics, Technische Universität Dresden, Dresden, Germany

Sergei Chakhlov School of Non-Destructive Testing and Security, Tomsk Polytechnic University, Tomsk, Russia

**Jian Chen** School of Optical-Electrical and Computer Engineering, University of Shanghai for Science and Technology, Shanghai, China

**Zhenmao Chen** State Key Laboratory for Strength and Vibration of Mechanical Structures Shaanxi ERC for NDT and Structural Integrity Evaluation School of Aerospace, Xi'an Jiaotong University, Xian, China

Luca Chiari Department of Applied Chemistry and Biotechnology, Graduate School of Engineering, Chiba University, Chiba, Japan

Younho Cho School of Mechanical Engineering, Pusan National University, Busan, South Korea

**J. Darrell Comins** School of Physics, Materials Physics Research Institute and DST-NRF Centre of Excellence in Strong Materials, University of the Witwatersrand, Johannesburg, South Africa

**Hongbo Cong** Department of Chemical and Biomolecular Engineering, Corrosion Engineering Program, The University of Akron, Akron, OH, USA

**Victor Hugo C. de Albuquerque** Programa de Pós Graduação em Informática Aplicada, Universidade de Fortaleza (UNIFOR), Fortaleza, Ceará, Brazil

**Yiming Deng** NDE Laboratory, Department of Electrical and Computer Engineering, Michigan State University, East Lansing, MI, USA

Marco Endrizzi University College London, London, UK

**Rudolph M. Erasmus** School of Physics, Materials Physics Research Institute and DST-NRF Centre of Excellence in Strong Materials, University of the Witwatersrand, Johannesburg, South Africa

Microscopy and Microanalysis Unit, University of the Witwatersrand, Johannesburg, South Africa

Arthur G. Every School of Physics, University of the Witwatersrand, Johannesburg, South Africa

Agnes Eydam Institute of Solid State Electronics, Technische Universität Dresden, Dresden, Germany

Paul Fromme Department of Mechanical Engineering, UCL, London, UK

Theobald O. J. Fuchs Fraunhofer EZRT, Fürth, Germany

**Masanori Fujinami** Department of Applied Chemistry and Biotechnology, Graduate School of Engineering, Chiba University, Chiba, Japan

**Tobias Gaul** Fraunhofer Institute for Ceramic Technologies and Systems IKTS, Dresden, Germany

Gerald Gerlach Institute of Solid State Electronics, Technische Universität Dresden, Dresden, Germany

Victor Giurgiutiu University of South Carolina, Columbia, SC, USA

Jonas Golde Clinical Sensoring and Monitoring, Anesthesiology and Intensive Care Medicine, Faculty of Medicine Carl Gustav Carus, TU Dresden, Dresden, Germany

**Christian U. Grosse** Center for Building Materials, Chair of Non-destructive Testing, Technical University of Munich, München, Germany

**Wolfgang R. Habel** Department of Non-Destructive Testing, Division of Fibre Optic Sensors, BAM Federal Institute for Materials Research and Testing (formerly), Berlin, Germany

Xiaoyan Han Department of Electrical and Computer Engineering, Wayne State University, Detroit, MI, USA

Randolf Hanke Fraunhofer IZFP, Saarbrucken, Germany

Christoph Heinzl University of Applied Sciences Upper Austria, Wels, Austria

Hans-Rüdiger Herzer Fraunhofer Institute for Nondestructive Testing IZFP, Saarbrücken, Germany

Henning Heuer Systems for Testing and Analysis, Fraunhofer IKTS, Dresden, Germany

Susanne Hillmann Accredited Test Lab, Fraunhofer IKTS, Dresden, Germany

Raffael Hipp Ultrasonic Sensors and Methods, Fraunhofer IKTS, Dresden, Germany

Nathan Ida Department of Electrical and Computer Engineering, The University of Akron, Akron, OH, USA

**Philipp Jatzlau** Center for Building Materials, Non-destructive Testing, Technical University of Munich, München, Germany

**Cherdpong Jomdecha** State Key Laboratory for Strength and Vibration of Mechanical Structures Shaanxi ERC for NDT and Structural Integrity Evaluation School of Aerospace, Xi'an Jiaotong University, Xian, China

**Joachim Jonuscheit** Fraunhofer Institute for Industrial Mathematics ITWM, Kaiserslautern, Germany

Anne Jüngert University of Stuttgart, Stuttgart, Germany

Johann Kastner University of Applied Sciences Upper Austria, Wels, Austria

Lars Kirsten Clinical Sensoring and Monitoring, Anesthesiology and Intensive Care Medicine, Faculty of Medicine Carl Gustav Carus, TU Dresden, Dresden, Germany

**Edmund Koch** Clinical Sensoring and Monitoring, Anesthesiology and Intensive Care Medicine, Faculty of Medicine Carl Gustav Carus, TU Dresden, Dresden, Germany

Bernd Köhler Accredited NDT Test Lab, Fraunhofer IKTS, Dresden, Germany

**Junrui Li** Optical Laboratory, Department of Mechanical Engineering, Oakland University, Rochester, MI, USA

**Shengxi Li** Department of Chemical and Biomolecular Engineering, Corrosion Engineering Program, The University of Akron, Akron, OH, USA

Weibin Li School of Aerospace Engineering, Xiamen University, Xiamen, China

**Uwe Lieske** Fraunhofer Institute for Ceramic Technologies and Systems IKTS, Dresden, Germany

Bin Lin Department of Mechanical Engineering, University of South Carolina, Columbia, SC, USA

X. Lucas Travassos Federal University of Santa Catarina, Joinville/Florianopolis, Brazil

Sheridan Mayo CSIRO Manufacturing, Clayton, VIC, Australia

Jennifer E. Michaels School of Electrical and Computer Engineering, Georgia Institute of Technology, Atlanta, GA, USA

**Udo Netzelmann** Fraunhofer-Institute for Nondestructive Testing IZFP, Saarbrücken, Germany

Christopher Niezrecki Department of Mechanical Engineering, University of Massachusetts Lowell, Lowell, MA, USA

Anna Pakuła Warsaw University of Technology, Warsaw, Poland

Mario Fernandez Pantoja Universidad de Granada, Granada, Spain

**Krzysztof Patorski** Department of Mechatronics, Institute of Micromechanics and Photonics, Warsaw University of Technology, Warsaw, Poland

**Vivek T. Rathod** NDE Laboratory, Department of Electrical and Computer Engineering, Michigan State University, East Lansing, MI, USA

**Guglielmo Rubinacci** Department of Electrical Engineering and Information Technology, Università degli Studi di Napoli Federico II, Napoli, Italy

Alessandro Sabato Department of Mechanical Engineering, University of Massachusetts Lowell, Lowell, MA, USA

Ali Sadr School of Electrical Engineering, Iran University of Science and Technology (IUST), Narmak, Tehran, Iran

Joanna Schmit 4D Technology, Tucson, AZ, USA

**Christian Schnabel** Clinical Sensoring and Monitoring, Anesthesiology and Intensive Care Medicine, Faculty of Medicine Carl Gustav Carus, TU Dresden, Dresden, Germany

**Dieter Schneider** Fraunhofer Institute for Material and Beam Technology (IWS), Dresden, Germany

Eckhardt Schneider Fraunhofer Institute for Nondestructive Testing IZFP, Saarbrücken, Germany

Frank Schubert Ultrasonic Sensors and Methods, Fraunhofer IKTS, Dresden, Germany

Martin H. Schulze Eddy Current Methods, Fraunhofer IKTS, Dresden, Germany

**Gunnar Suchaneck** Institute of Solid State Electronics, Technische Universität Dresden, Dresden, Germany

Klaus Szielasko Fraunhofer Institute for Nondestructive Testing IZFP, Saarbrücken, Germany

Antonello Tamburrino Department of Electrical and Information Engineering, Università degli Studi di Cassino e del Lazio Meridionale, Cassino, Italy

Department of Electrical and Computer Engineering, Michigan State University, East Lansing, MI, USA

Brian K. Tanner Department of Physics, Durham University, Durham, UK

João Manuel R. S. Tavares Instituto de Ciência e Inovação em Engenharia Mecânica e Engenharia Industrial, Faculdade de Engenharia, Universidade do Porto, Porto, Portugal

**Wolfgang Treimer** Department Mathematics-Physics-Chemistry, University of Applied Sciences Beuth Hochschule für Technik Berlin, Berlin, Germany

**Maciej Trusiak** Department of Mechatronics, Institute of Micromechanics and Photonics, Warsaw University of Technology, Warsaw, Poland

**Eleni Tsangouri** Department of Mechanics of Materials and Constructions (MeMC), Vrije Universiteit Brussel (VUB), Brussels, Belgium

**Kilian Tschöke** Fraunhofer Institute for Ceramic Technologies and Systems IKTS, Dresden, Germany

**Ralf Tschuncky** Fraunhofer Institute for Nondestructive Testing IZFP, Saarbrücken, Germany

**Bart Van Damme** Empa, Swiss Federal Laboratories for Materials Science and Technology, Dubendorf, Switzerland

Vladimir P. Vavilov Tomsk Polytechnic University, Tomsk, Russia

**Masoud Vejdannik** School of Electrical Engineering, Iran University of Science and Technology (IUST), Narmak, Tehran, Iran

Julia Walther Clinical Sensoring and Monitoring, Anesthesiology and Intensive Care Medicine, Faculty of Medicine Carl Gustav Carus, TU Dresden, Dresden, Germany

**Bianca Weihnacht** Fraunhofer Institute for Ceramic Technologies and Systems IKTS, Dresden, Germany

**Shejuan Xie** State Key Laboratory for Strength and Vibration of Mechanical Structures Shaanxi ERC for NDT and Structural Integrity Evaluation School of Aerospace, Xi'an Jiaotong University, Xian, China

Lianxiang Yang Optical Laboratory, Department of Mechanical Engineering, Oakland University, Rochester, MI, USA

**Qiwen Zhan** School of Optical-Electrical and Computer Engineering, University of Shanghai for Science and Technology, Shanghai, China

Department of Electro-Optics and Photonics, University of Dayton, Dayton, OH, USA

**Qixin Zhou** Department of Chemical and Biomolecular Engineering, Corrosion Engineering Program, The University of Akron, Akron, OH, USA

Marek Ziolkowski Technische Universitaet Ilmenau, Ilmenau, Germany

West Pomeranian University of Technology Szczecin, Szczecin, Poland